

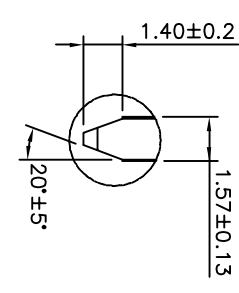
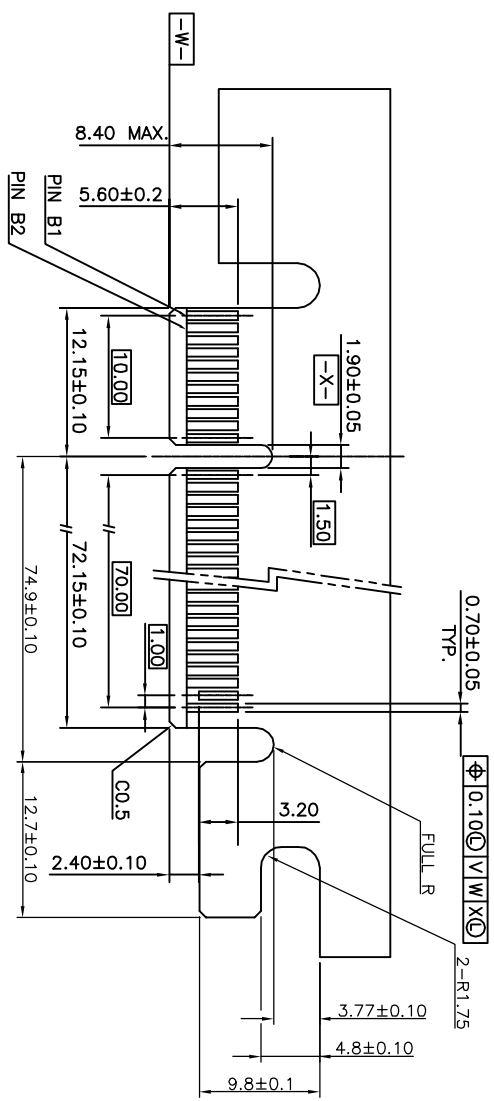
SEC A-A

SEC B-B
SECALE 2:1

mat'l. code		tr		ecn no		dr		dtdt		linear		tolerances unless otherwise specified		CUSTOMER COPY		title	
A		T05-0046		J.H		2/23/05		.XX ± 0.25		.XX ± 0.10		.X ± 0.38		projection		PCI-E INTEGRATED TYPE	
B		T05-0067		J.H		3/28/05		.XXX ± 0.10		0° ± 2°		.X ± 0.25		MM		CARD EDGE ASS'Y	
C		T05-0227		J.H		09/30/05		dr		JASON HSU		2/23/05		scdle		product family	
D		T06-0187		J.H		11/13/06		dr		JASON HSU		2/23/05		1:1		EDGE CARD	
E		T07-1125		J.H		08/02/07		engr		STERLING LIN		2/23/05		A4		size dwg no	
sheet		revision		1		E		2		E		3		code		TWN	
index		sheet		1		E		2		E		3		sheet		1 of	

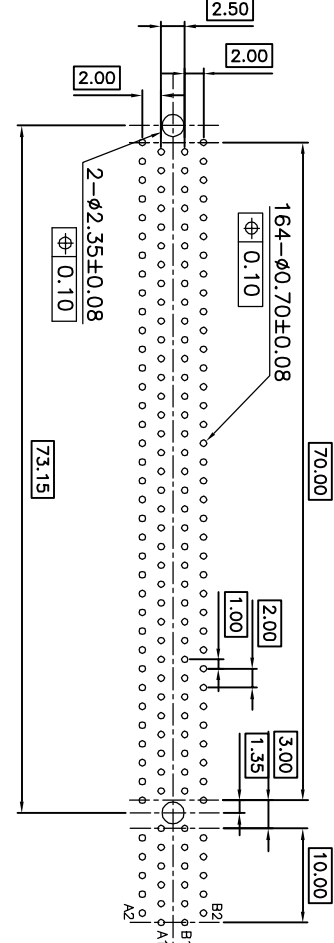
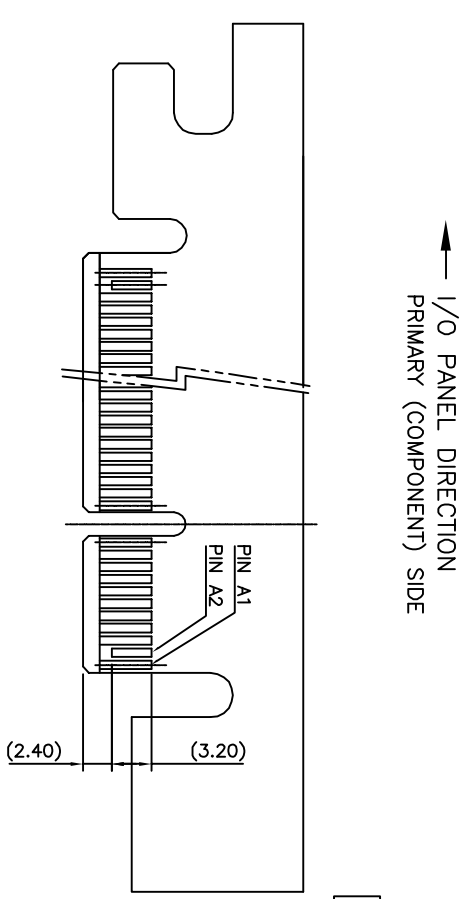
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page code
22526



SCALE 2:1

ADD-IN CARD EDGE-FINGER DIMENSIONS



RECOMMENDED FOOTPRINT LAYOUT

I/O PANEL DIRECTION
SECONDARY (SOLDER) SIDE

I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE

mod'l. code	tolerances unless otherwise specified		CUSTOMER COPY	FCI	www.fciconnect.com
itr	ecn no	dr	date	linear	.XX ± 0.25
E				angles	° ± 2°
				dr	JASON HSU 2/23/05
				engr	JASON HSU 2/23/05
				chr	STERLING LIN 2/23/05
				qppd	HC LIU 2/23/05
sheet	revision			scale	1:1
index	sheet			product family	EDGE CARD
				size dwg no	10046742
				code	TWN
				sheet	2 of

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code code
22526

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3

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NOTES: 1. MATERIAL:

HOUSING: THERMOPLASTIC WITH GLASS FIBER, UL94V-0, COLOR IN BLACK.
LATCHES: THERMOPLASTIC WITH GLASS FIBER, UL94 HB, COLOR IN BLACK.
CONTACTS: COPPER ALLOY.
BOARDLOCKS: COPPER ALLOY.

2. FINISH:

CONTACTS: GOLD PLATING ON CONTACT AREA,
100u"MIN. TIN/LEAD OR 60u" MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDERTAILS,
50u"MIN. NICKEL UNDERPLATING OVER ALL.
BOARDLOCKS : 100u" TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDERTAILS,
50u"MIN. NICKEL UNDERPLATING OVER ALL.

3. WARNING: THE MAXIMUM ALLOWABLE ANGLE TO WITHDRAWAL THE DAUGHTER CARD FROM RETAINER BY 20 DEGREE.
4. DURABILITY: 50 CYCLES.

5. ROHS COMPATIBLE PRODUCT SPECIFICATIONS

a. PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE, 2.5um min. MATTE PURE TIN OVER 1.27um MIN. NICKEL UNDERPLATE.
b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260C±5C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60MM THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE

10046742 -X X X X X X X X LF

APPLICATIONS

BLANK - LEAD CONTAIN FOR PLATING OPTIONS 3,4,5
LF - LEAD FREE FOR PLATING OPTIONS 0,1,2

HOUSING COLOR OPTIONS

- 1-BLACK FOR BASE & RM
- 2-BLACK FOR BASE & WHITE FOR RM
- 3-BLUE (287U) FOR BASE & RM
- 4-BLUE (297U) FOR BASE & RM

PEGS OPTIONS

- 1-METAL & PLASTIC COMPOUND

TERMINAL PLATING OPTIONS

- 0-50u" Ni: UNDERPLATE
- 30u" Au CONTACT AREA
- 100u" TIN TAIL AREA
- 1-50u" Ni: UNDERPLATE
- 15u" Au CONTACT AREA
- 100u" TIN TAIL AREA
- 2-50u" Ni: UNDERPLATE
- GOLD FLASH CONTACT AREA
- 100u" TIN TAIL AREA
- 3-50u" Ni: UNDERPLATE
- 30u" Au CONTACT AREA
- 100u" TIN/LEAD TAIL AREA
- 4-50u" Ni: UNDERPLATE
- 15u" Au CONTACT AREA
- 100u" TIN/LEAD TAIL AREA
- 5-50u" Ni: UNDERPLATE
- GOLD FLASH CONTACT AREA
- 100u" TIN/LEAD TAIL AREA

TAIL LENGTH OPTION (DIM A)

- 1- 3.10MM
- 2- 2.30MM

PACKAGING OPTIONS

- T-TRAY PACKAGING

POS OPTIONS

- 3-164

mat'l. code	ecn no	dr	date	linear	tolerances unless otherwise specified	projection	title	product family	code
E				.XX ± 0.25		MM	PCI-E INTEGRATED TYPE CARD EDGE ASSY	EDGE CARD	TWIN
				.XXX ± 0.10					3 of
				0 ±.2"					
				dr JASON HSU 2/23/05					
				engr JASON HSU 2/23/05					
				chr STERLING LIN 2/23/05					
				pppl HC LIOU 2/23/05					
sheet	revision								
index	sheet								

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ACAD

code code
22526